

High Density Low Profile Connectors

- High density contact arrangement
- Light weight Low profile mated height
- Surface mount termination technology
- Miniature hyperboloid socket contacts
- Interfacial seal
- Polarized and scoop proof
- Pick and place compatible

General Specifications	
Insulator Material	Liquid crystal polymer (LCP)
Contact Material	Copper alloy
Socket Wire Material	Beryllium copper
Interfacial Seal Material	Fluorosilicone
Guides Material	Stainless steel
Contact Plating	ASTM-488-B (Type II, grade C, Class 1)
Contact Resistance	8 milliohms max.
Current Rating	2 Amps per contact
Contact Life Cycles	2,000+ operations
Extraction Forces	1.0 oz.
Temperature Range	-55° C to 125° C
Voltage Rating	110 VDC or AC peak nomial
Contact Diameter	0.015 [0.39]

Current Rating

The Hypertac® contact design and manufacturing tolerances endow the product with the following attributes:

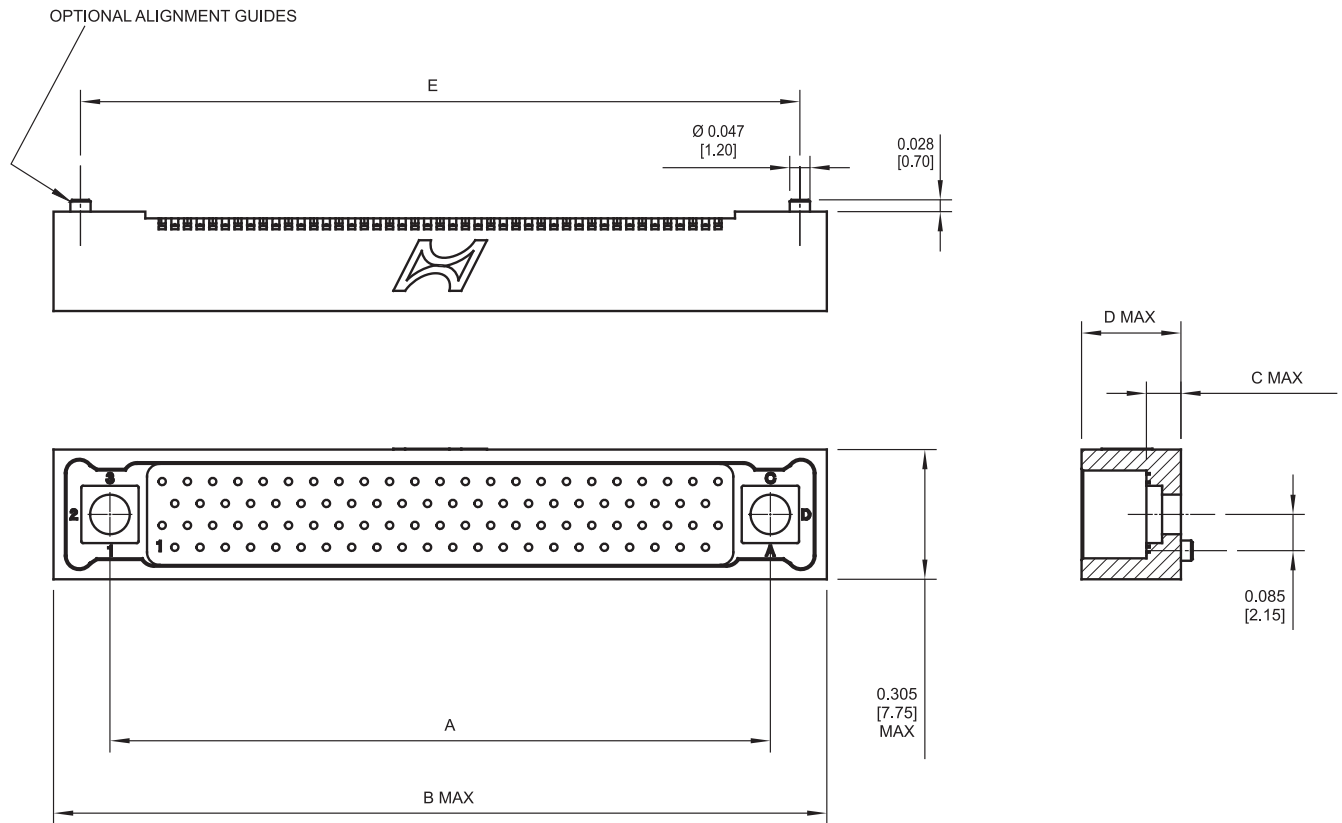
- Double the current rating of other contact designs of similar size
- Low contact resistance in high current applications minimizes temperature rise thereby enabling higher density interconnects

Contact Plating Finishes					
Connector Finish Ordering Code	Description	Component	Component Finish Ordering Code	Conforms To	Plating Thickness*
U	Gold Plate	Socket	-/9	ASTM-488-B (Type II, Grade C, Class 1)	1.27 µm gold plate min. 50 µin gold plate min.
		Pin	-/7	ASTM-488-B (Type II, Grade C, Class 1)	1.27 µm gold plate min. 50 µin gold plate min.

* PLATING THICKNESS
These values apply to mating surfaces.

Dimensions are in inches [mm]

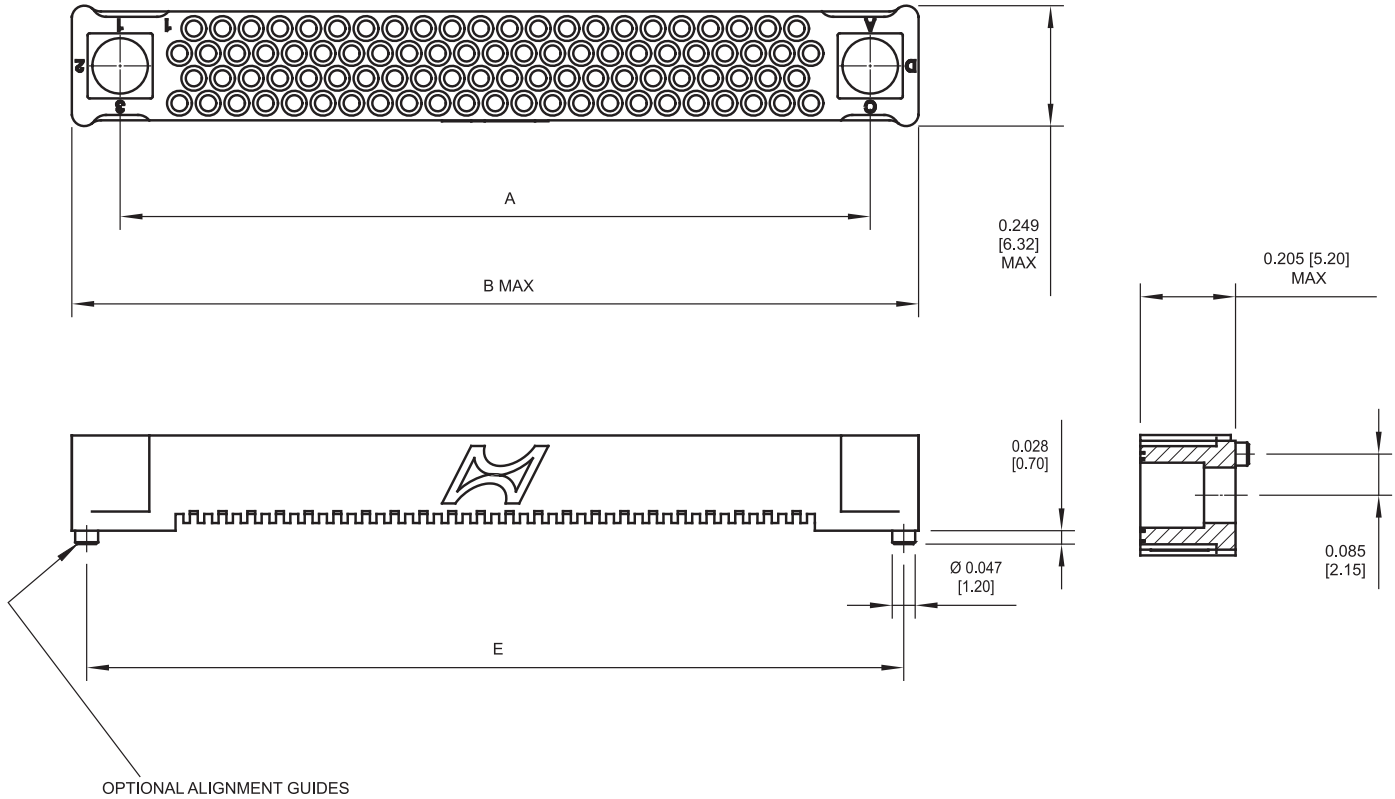
HDLP Insulators Straight Male



Straight Male								
Number of Contacts	30		58		90		118	
	Single	Double	Single	Double	Single	Double	Single	Double
Dimension A	0.657 [16.70]	-	1.070 [27.20]	-	1.543 [39.20]	-	1.957 [49.70]	-
Dimension B	0.923 [23.45]	-	1.337 [33.95]	-	1.809 [45.95]	-	2.222 [56.45]	-
Dimension C	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]	0.090 [2.28]	0.270 [6.85]
Dimension D	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]	0.243 [6.18]	0.423 [10.75]
Dimension E	0.795 [20.20]	-	1.209 [30.70]	-	1.681 [42.70]	-	2.094 [53.20]	-

Dimensions are in inches [mm]

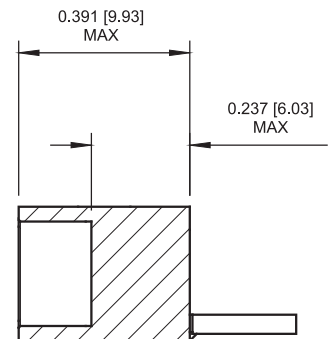
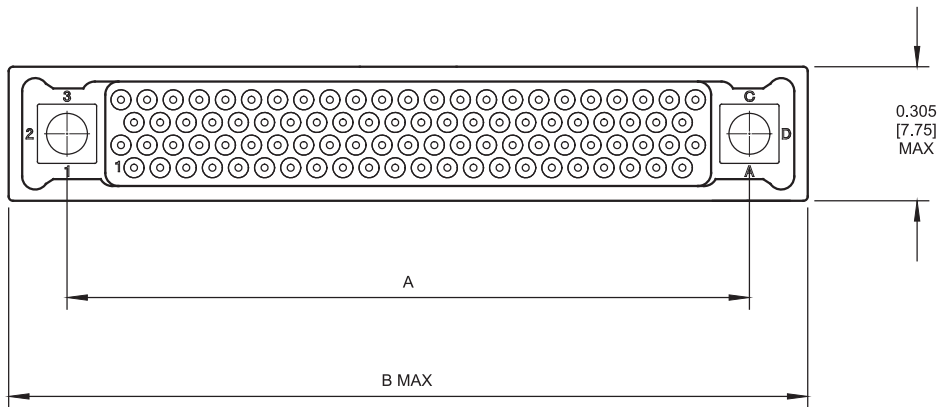
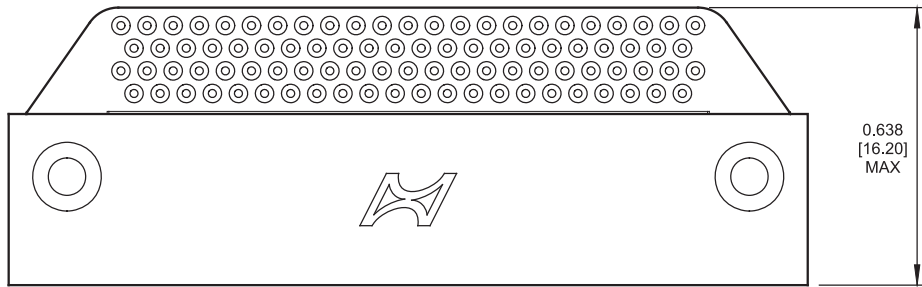
HDLP Insulators
Straight Female



Straight Female				
Number of Contacts	30	58	90	118
Dimension A	0.657 [16.70]	1.070 [27.20]	1.543 [39.20]	1.957 [49.70]
Dimension B	0.858 [21.80]	1.272 [32.30]	1.744 [44.30]	2.157 [54.80]
Dimension E	0.795 [20.20]	1.209 [30.70]	1.681 [42.70]	2.094 [53.20]

Dimensions are in inches [mm]

HDLP Insulators 90° Male

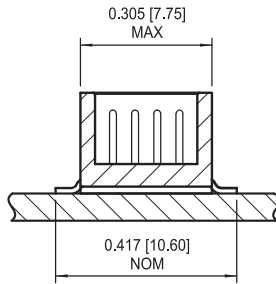


90° Male				
Number of Contacts	30	58	90	118
Dimension A	0.657 [16.70]	1.070 [27.20]	1.543 [39.20]	1.957 [49.70]
Dimension B	0.923 [23.45]	1.337 [33.95]	1.809 [45.95]	2.222 [56.45]

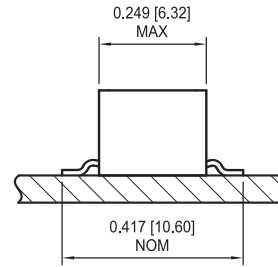
Dimensions are in inches [mm]

HDLP Contact Terminations

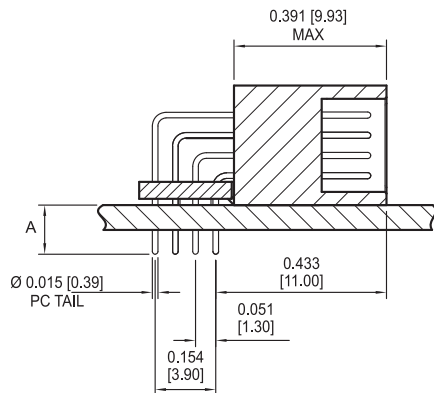
Male SMT



Female SMT

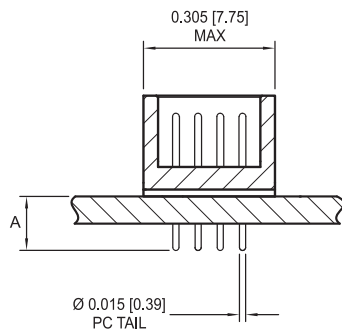


Male 90° Printed Circuit Board

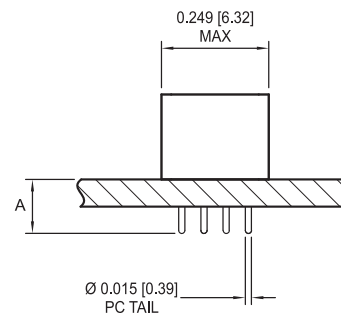


Termination Style	Dimension A
H	0.089 [2.26]
J	0.124 [3.16]
K	0.152 [3.86]

Male Vertical Printed Circuit Board



Female Vertical Printed Circuit Board



Termination Style	Dimension A
C	0.089 [2.26]
D	0.124 [3.16]
E	0.152 [3.86]

Termination Style	Dimension A
C	0.089 [2.26]
D	0.124 [3.16]
E	0.152 [3.86]

Dimensions are in inches [mm]

HDLP Part Number Configurator

HDLP
1
1
030
U
F
H
AA
OPO

Series	HDLP
Alignment Pips	1 = With 2 = Without Default is 2 if insulator style is 9
Insulator Height/Style	1 = Single 2 = Double 9 = 90° Default is 9 for 90° contact termination (90° female not currently available)
Number of Contacts	030 = 30 058 = 58 090 = 90 118 = 118
Contact Plating	U = Standard gold plating 50µin gold plating over 50µin nickel plating over 10µin copper flash S = Gold plate with tin dipped terminations (PC tail only)
Contact Gender	M = Male F = Female

Standard Variations	(Male and Female Printed Circuit Board Variants) OPO = Back potted terminations and fitted with interfacial seal (preferred) OPX = Tinned and back potted and fitted with interfacial seal (preferred) OPC = Back potted, coated to conformity and fitted with interfacial seal NPO = Back potted terminations (preferred) NPX = Tinned and back potted NPC = Back potted and coated to conformity
Guide Hardware	AA = No guide hardware B- = Locking socket C- = Not yet defined D- = Locking post E- = Not yet defined F- = Polarizing socket G- = Not yet defined H- = Polarizing Pin I- = Not yet defined J- = Connector to board fixing K- = Not yet defined L- = Guide socket M- = Not yet defined O- = Guide Pin P- = Not yet defined Q- = Polarized transverse mounting (Contact factory for more details)
Contact Termination	C = Through board solder-Straight PC Tail – 2.26mm Long D = Through board solder-Straight PC Tail – 3.16mm Long E = Through board solder-Straight PC Tail – 3.86mm Long H = Through board solder- 90° PC Tails – 2.26mm Long J = Through board solder- 90° PC Tails – 3.16mm Long K = Through board solder- 90° PC Tails – 3.86mm Long Q = Surface Mount - Straight (Contact factory for more details)

Dimensions are in inches [mm]